



News Release

FOR IMMEDIATE RELEASE

Change to Recent News Release Entitled “Final Agreement Reached on the Sale of Hiroshima Elpida's 200mm Wafer Processing Equipment”

TOKYO, JAPAN, August 30, 2007 – Elpida Memory, Inc. (Elpida), Japan's leading global supplier of Dynamic Random Access Memory (DRAM), together with its consolidated subsidiary Hiroshima Elpida Memory, Inc. (Hiroshima Elpida), today announced a change of information in a news release distributed on April 10, 2007 entitled “Final Agreement Reached on the Sale of Hiroshima Elpida's 200mm Wafer Processing Equipment.” The change appears below and is underlined.

Original News Release (April 10, 2007)

1. Asset transfer details

Assets to be transferred: Hiroshima Elpida's 200mm wafer processing equipment
(Total wafer processing capacity: approx. 50,000 wafers/month)
Location of assets: 7-10, Yoshikawa Kogyo Danchi, Higashi Hiroshima-shi, Hiroshima, Japan
Asset transfer price: US\$320 million

Changed News Release (see underline)

1. Asset transfer details

Assets to be transferred: Hiroshima Elpida's 200mm wafer processing equipment
(Total wafer processing capacity: approx. 50,000 wafers/month)
Location of assets: 7-10, Yoshikawa Kogyo Danchi, Higashi Hiroshima-shi, Hiroshima, Japan
Asset transfer price: US\$309.5 million

Reason for Change

Partial adjustment of the assigned assets.

Please note that the change should not affect our consolidated results for the current business year.

About Elpida Memory, Inc.

Elpida Memory, Inc., (Tokyo Stock Exchange Code 6665), is a leading manufacturer of Dynamic Random Access Memory (DRAM) silicon chips. Our design, manufacturing, and sales operations are backed by our world class technology expertise. Our manufacturing facilities, Hiroshima Elpida Memory, Inc. (front-end processes) and Akita Elpida Memory, Inc. (back-end processes), utilize the most advanced manufacturing technologies available in the industry. Further, we have customer sales and marketing support offices in Japan, North America, Europe, Taiwan, Hong Kong and Singapore. Elpida's portfolio of advanced products features such characteristics as high-density, high-speed, low power and small packing profiles. We provide applications across a wide range of areas, including high-end servers, mobile phones and digital consumer electronics. For more information about Elpida, please visit <http://www.elpida.com>.

Information in this news release is current as of the timing of the release, but may be revised later without notice.

Elpida Press Contacts:

Corporate Communication Group
Elpida Memory, Inc. (Japan)
Tel: +81-3-3281-1648
E-mail: press@elpida.com

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